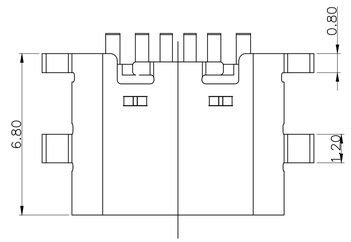
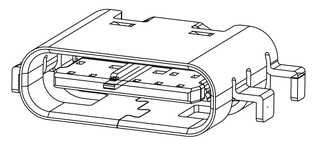
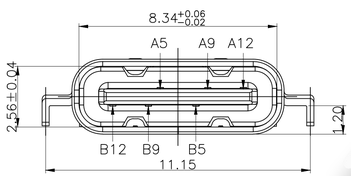
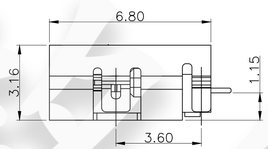
REV	DESCRIPTION	DATE	APPROVED

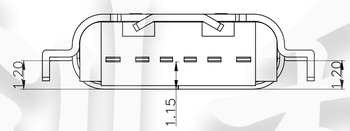
ROHS Compliant REACH

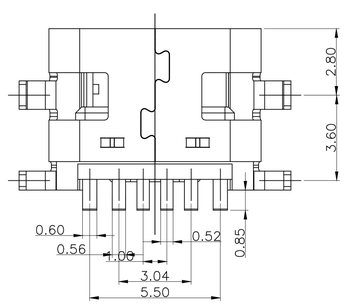


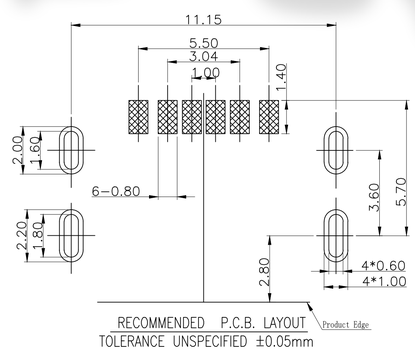












NOTE:

1.MATERIAL SPECIFICATION:
  1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
  2.CONTACTS:COPPER ALLOY
  3.MID PLATE: STAINLESS STEEL
  4.FRONT SHELL: STAINLESS STEEL

2.PLATING SPECIFICATION:
  2-1.CONTACTS:
  Ni 50u" MIN. UNDER PLATED OVER ALL.
  Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
  (GOLD PLATING THICKNESS FOLLOW THE P/N)
  PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

2-2.FRONT SHELL:
  SEE TABLE1.

2-3.SHIELD PLATE&EMI PLATE:
  CLEAR ONLY

3.MECHANICAL PERFORMANCE,
  3-1.INSERTION FORCE: 0.5~2.0kgf.
  3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
  3-3.DURABILITY: 5000 CYCLES.

4.ELECTRICAL PERFORMANCE,
  4-1. CURRENT RATING:3.0A
  VOLTAGE RATING:5.0V
  4-2. LLCR:
  VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
  SHIELD: 50mΩ/MAX.
  LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
  4-3.INSULATION RESISTANCE: 100MΩ MIN
  4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:
  OPERATING TEMPERATURE: -25°C~+85°C.

6.IR REFLOW:
  THE PEAK TEMPERATURE ON THE BOARD SHALL
  BE MAINTAINED FOR 10 SECONDS AT 260°C.

铭创科技

PIN ASSIGNMENTS

A5	CC1	B12	GND
A9	VBUS	B9	VBUS
A12	GND	B5	CC2
PIN	SIGNAL NAME	PIN	SIGNAL NAME

CUSTOMER DRAWING		铭创科技（东莞）有限公司 Mingchuang Technology (Dongguan) Co., Ltd.
UNITS: mm	SCALE: 1:1	SHEET
PROJECTION:	DRAW: DAP	TITLE: TYPE C母座6PIN 沉板1.2 四脚插板SMT L=6.8
GENERAL TOLERANCE 0.0 ±0.35 0.00 ±0.20 0.000 ±0.10 0.° ±10° 0.0° ±8° 0.00° ±5°	CHECK: HWT	MAT'L: SEE TABLE / FINISH: SEE TABLE
	APPD: HHM	DWG. NO. 0038.TCF.6CB.H97 / PART NO. _____ / SIZE A4